US00D922609S

(12) **United States Design Patent**
Tokimatu et al.

(10) **Patent No.: US D922,609 S**
(45) **Date of Patent: ** Jun. 15, 2021**

(54) **HOLDING PAD FOR SUBSTRATE TRANSFER**

(71) Applicant: **TOKYO ELECTRON LIMITED**, Tokyo (JP)

(72) Inventors: **Toru Tokimatu**, Koshi (JP); **Akihiro Teramoto**, Koshi (JP)

(73) Assignee: **TOKYO ELECTRON LIMITED**, Tokyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/665,836**

(22) Filed: **Oct. 8, 2018**

(30) **Foreign Application Priority Data**

Apr. 20, 2018 (JP) 2018-008791

(51) **LOC (13) Cl.** **24-02**
(52) **U.S. Cl.**
USPC **D24/225**
(58) **Field of Classification Search**
USPC D24/110, 110.5, 169, 211, 223, 224, 225, D24/230; D10/74, 108; D8/352, 397; D23/225, 231, 232
CPC A61B 18/148; A61B 18/1482; A61B 18/1487; F04B 1/00; F04B 1/10; F04B 1/12
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D328,210	S	*	7/1992	Callon	D6/707.2
D451,374	S	*	12/2001	Shinjo	D8/397
D453,000	S	*	1/2002	Shinjo	D8/397
D463,968	S	*	10/2002	LaPlume	D8/352
D559,993	S	*	1/2008	Nagakubo	D24/232
D559,994	S	*	1/2008	Nagakubo	D24/232
D560,284	S	*	1/2008	Nagakubo	D24/232
D679,375	S	*	4/2013	Kenyon	D24/110
D684,694	S	*	6/2013	Green	A61B 17/132 D24/169
D684,695	S	*	6/2013	Green	D24/143
D685,461	S	*	7/2013	Striebig	D24/110
D697,224	S	*	1/2014	Judson	D24/216
D703,026	S	*	4/2014	Wu	D8/350
D736,261	S	*	8/2015	Bellinger	D15/28
D738,935	S	*	9/2015	Chu	D15/9
D755,038	S	*	5/2016	Bolton	D8/352

(Continued)

Primary Examiner — Susan Bennett Hattan
Assistant Examiner — Omeed Agilee
(74) *Attorney, Agent, or Firm* — Nath, Goldberg & Meyer; Jerald L. Meyer; Tanya E. Harkins

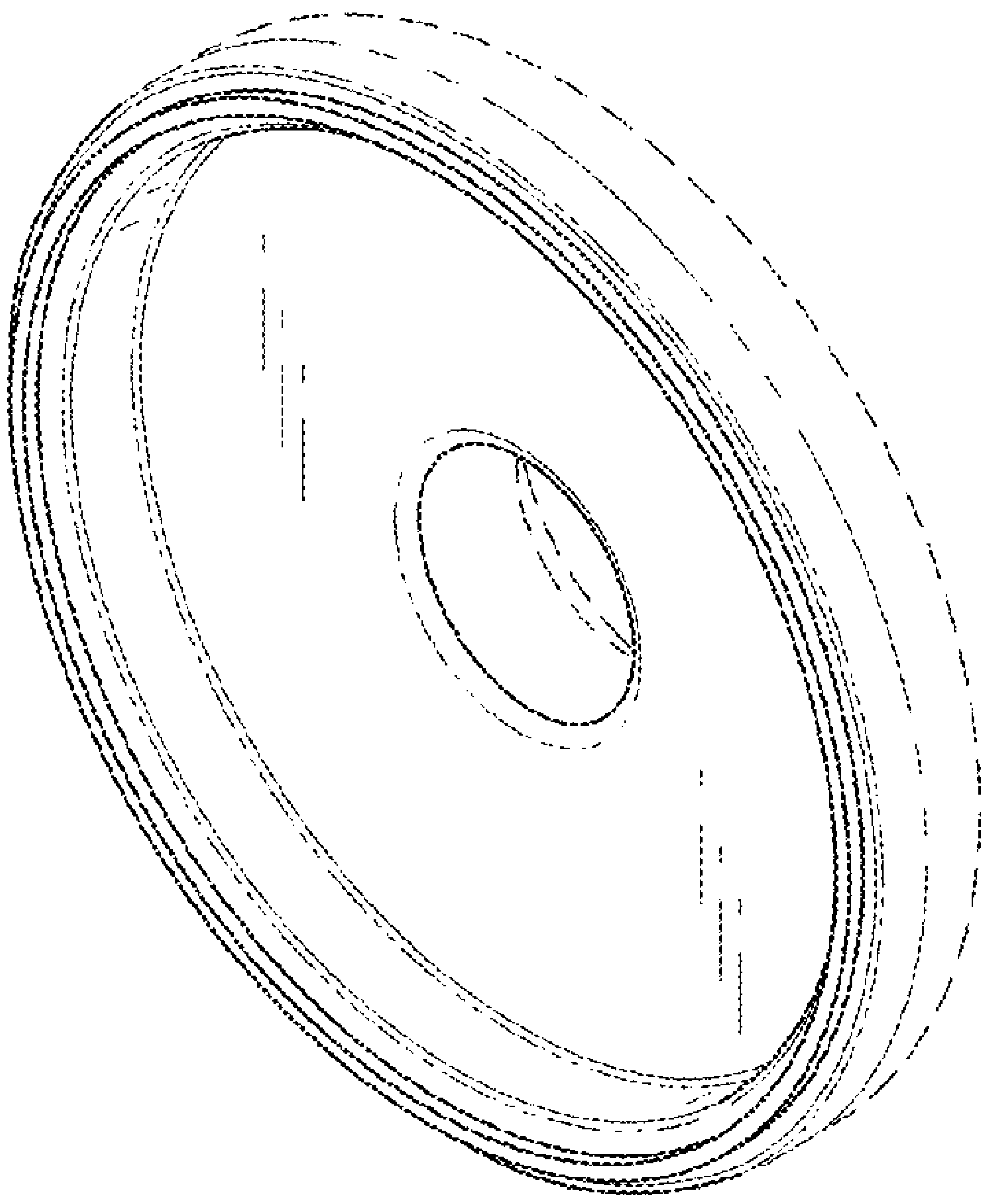
(57) **CLAIM**

The ornamental design for a holding pad for substrate transfer, as shown and described.

DESCRIPTION

FIG. **1** is an isometric view of a holding pad for substrate transfer showing our new design.
FIG. **2** is a reversed isometric view thereof.
FIG. **3** is a top plan view thereof.
FIG. **4** is a bottom plan view thereof.
FIG. **5** is a side elevational view thereof.
FIG. **6** is a cross sectional view thereof taken along cut lines **6-6** of FIG. **3**.
FIG. **7** is another side elevational view thereof.
FIG. **8** is another side elevational view thereof; and,
FIG. **9** is another side elevational view thereof.
The dashed lines in the drawings depict portions of the holding pad for substrate transfer that form no part of the claimed design. The dash-dot-dot lines in the drawings represent contours and shading and form no part of the claimed design. The short dash-short dash-long dash lines depict the boundaries of the claim and form no part thereof.

1 Claim, 9 Drawing Sheets



(56) **References Cited**

U.S. PATENT DOCUMENTS

D756,747	S	*	5/2016	Wu	D8/352
D855,207	S	*	7/2019	Ito	D24/225
D867,576	S	*	11/2019	Hewitt	D24/110
D878,548	S	*	3/2020	Lane	D24/110.5

* cited by examiner

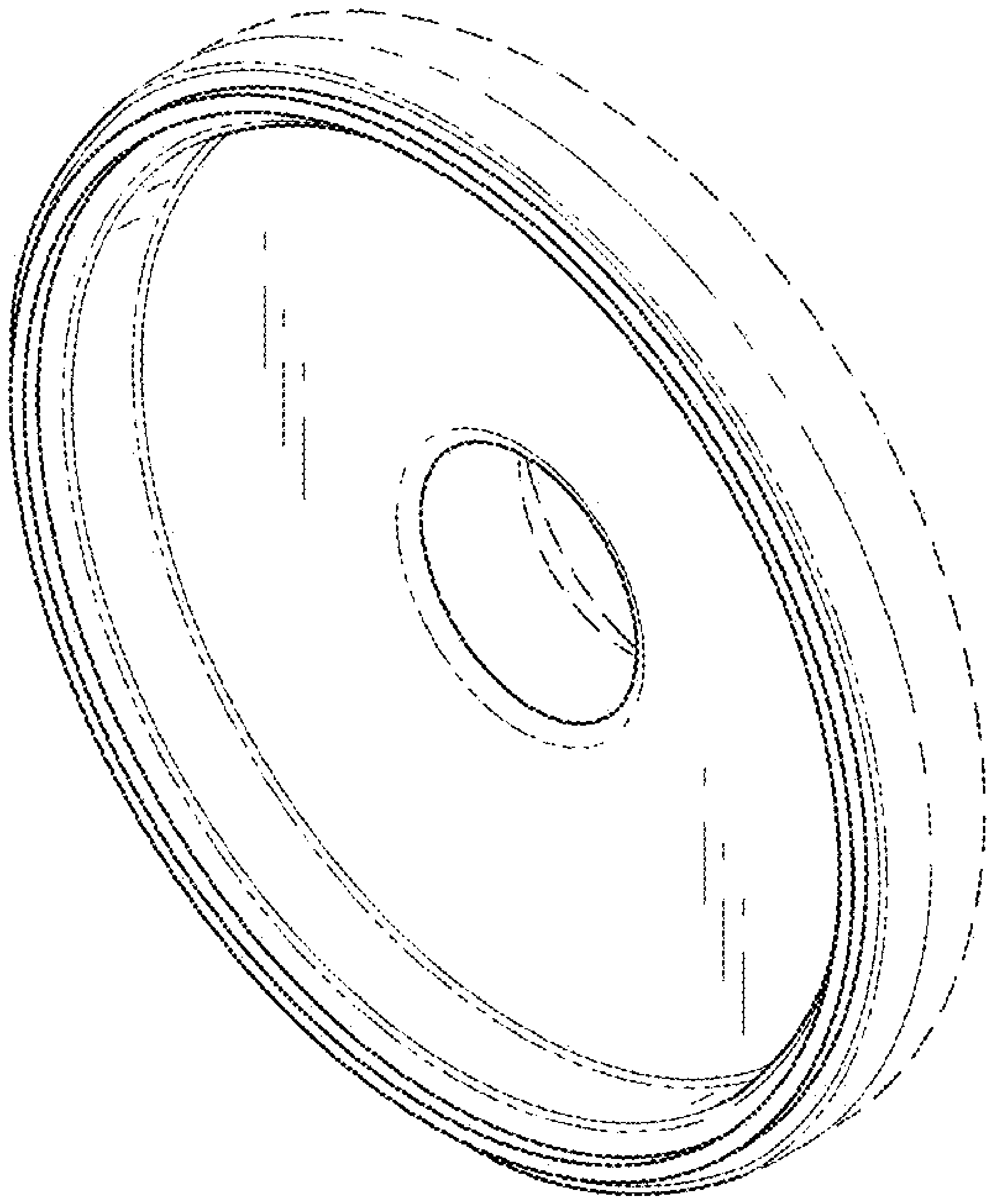


FIG. 1

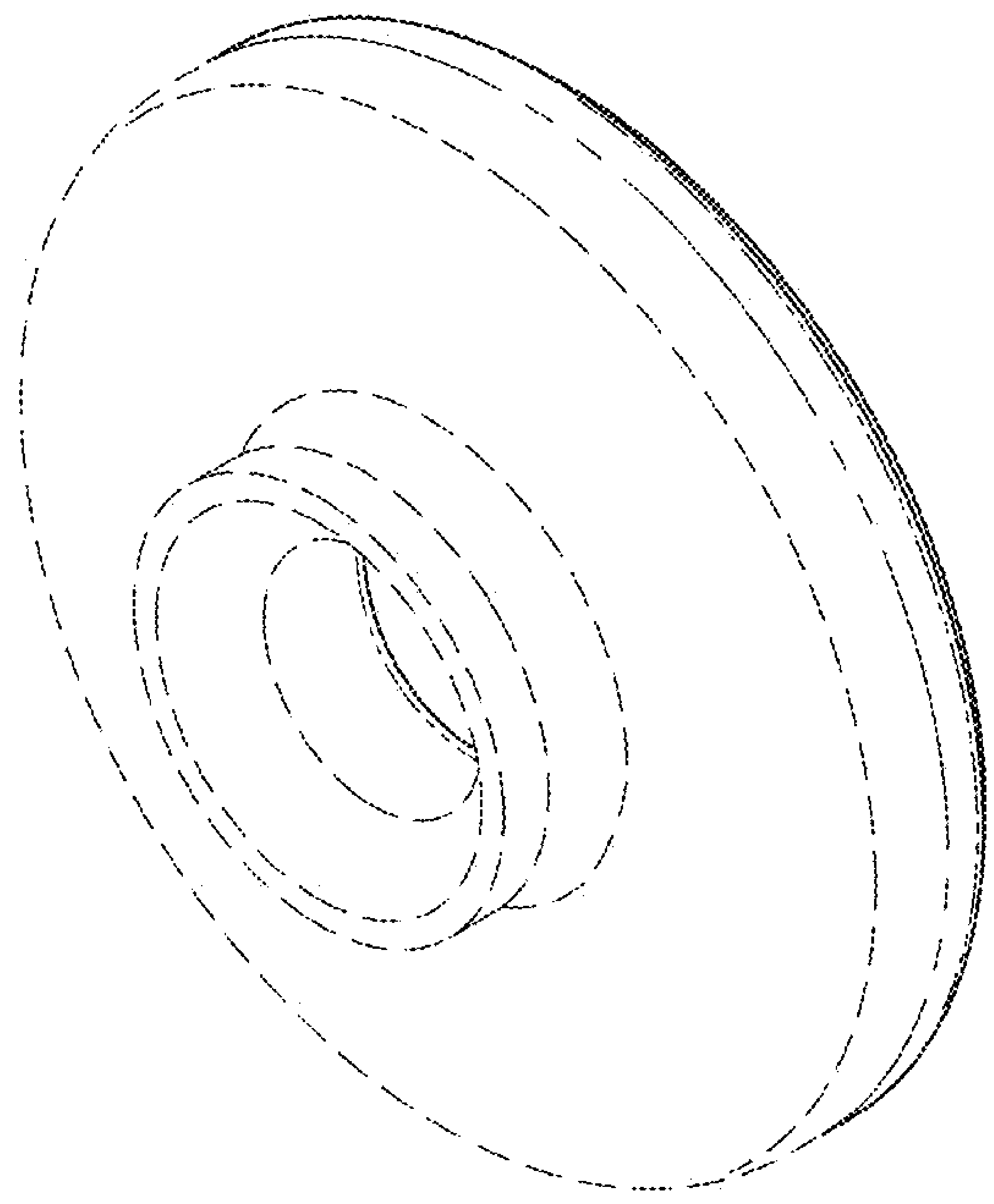


FIG. 2

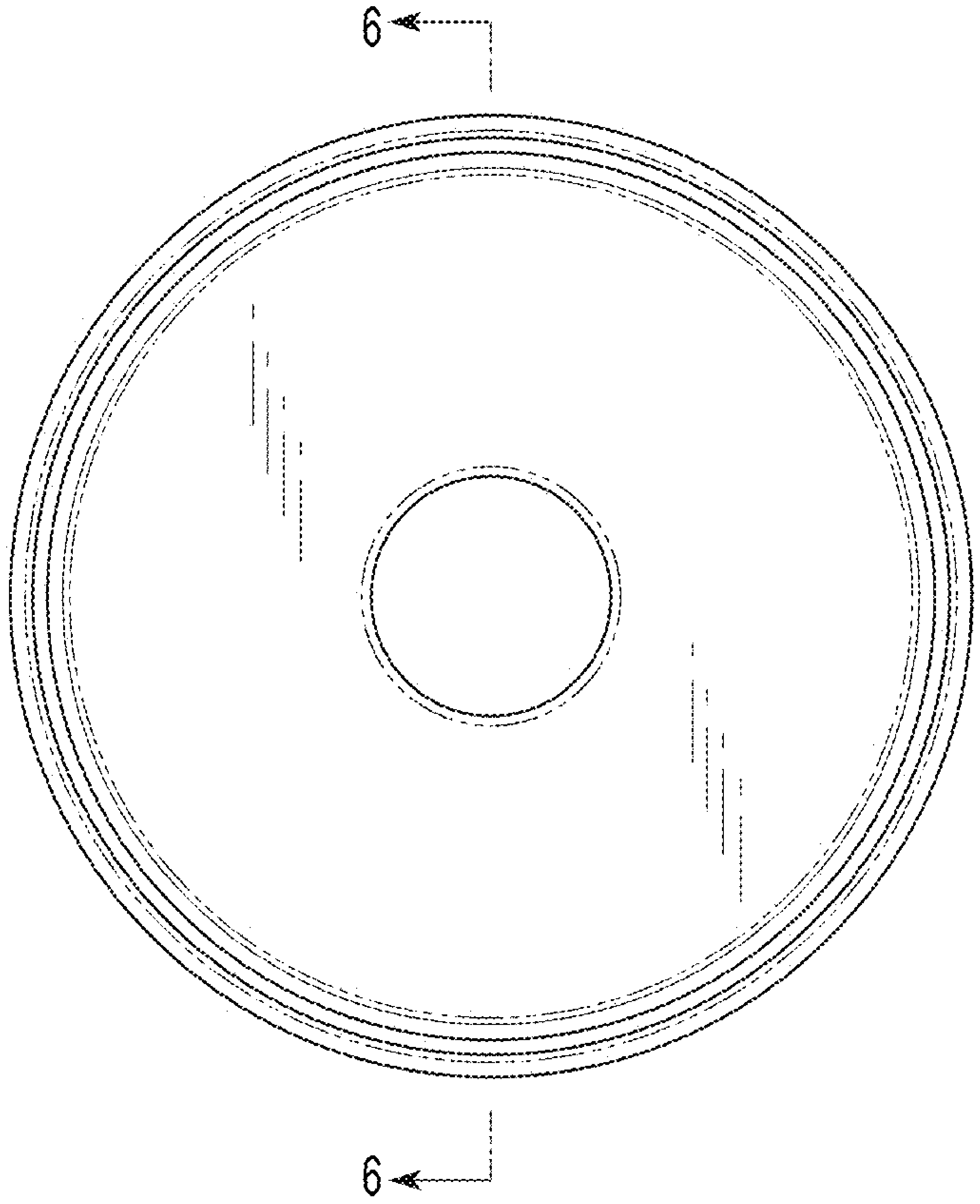


FIG. 3

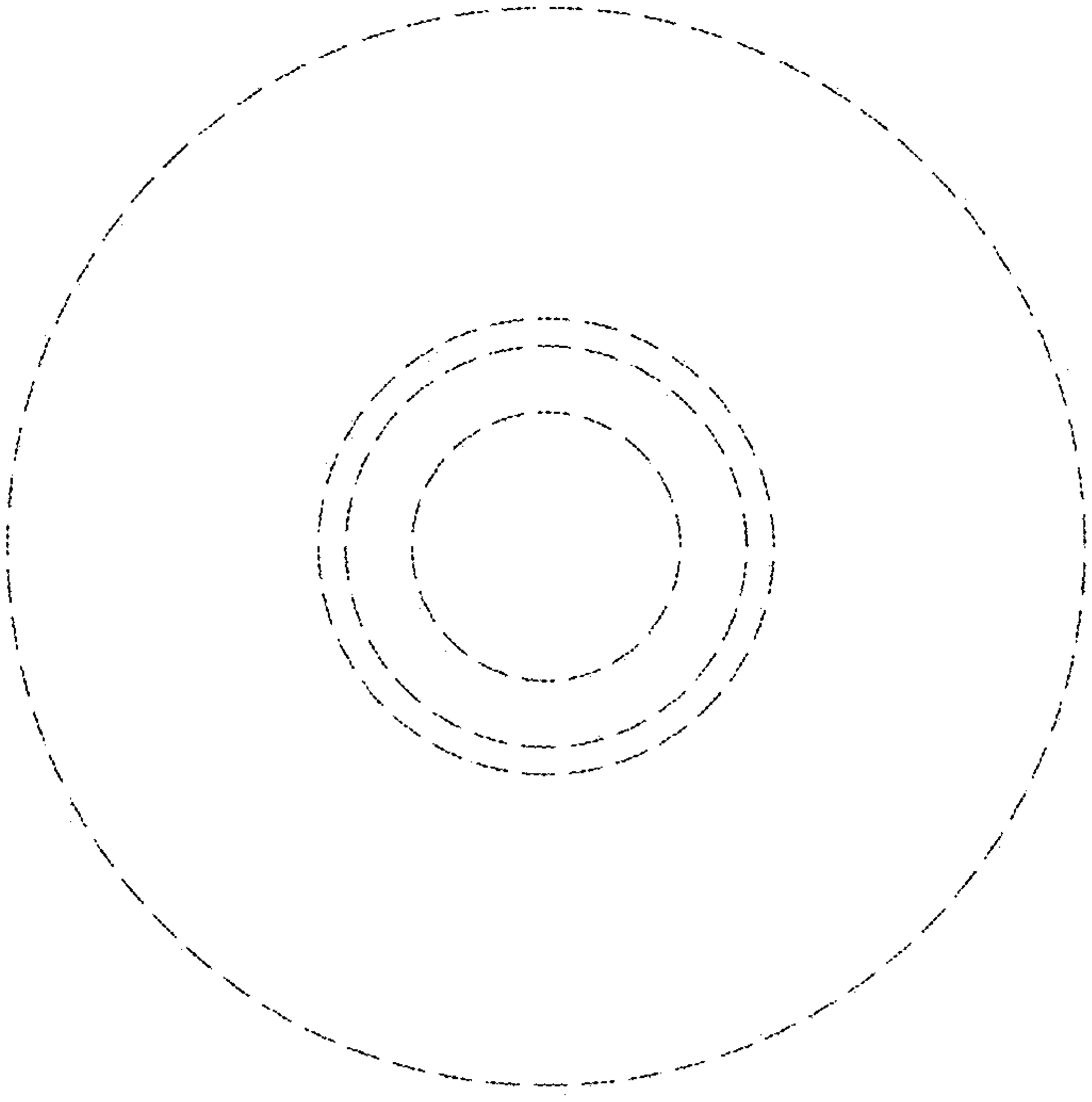


FIG. 4

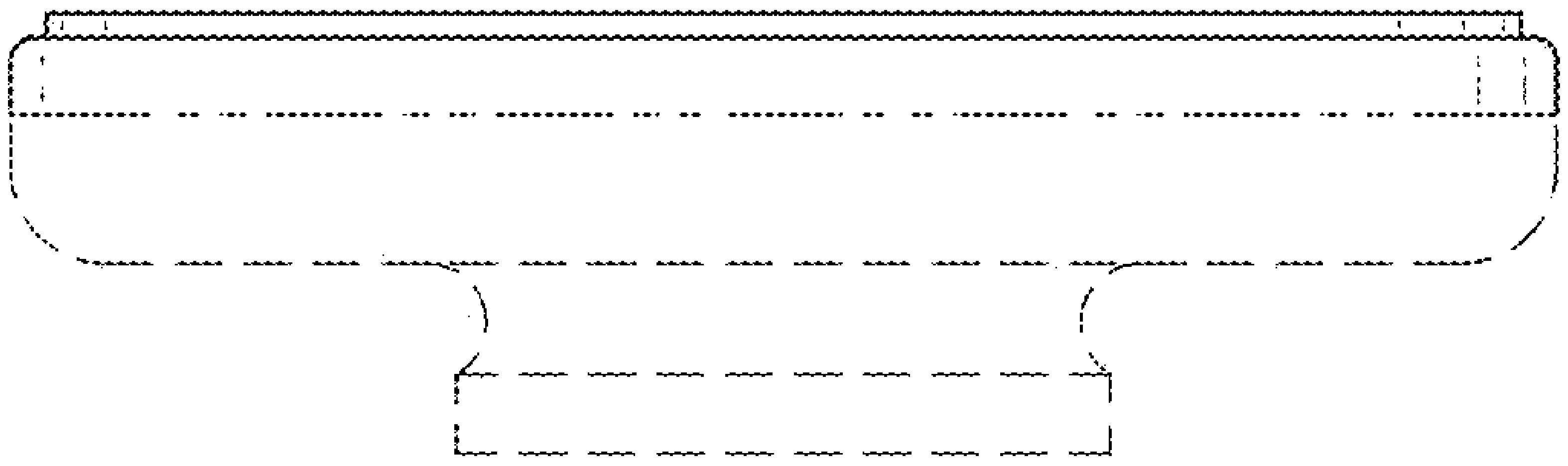


FIG. 5

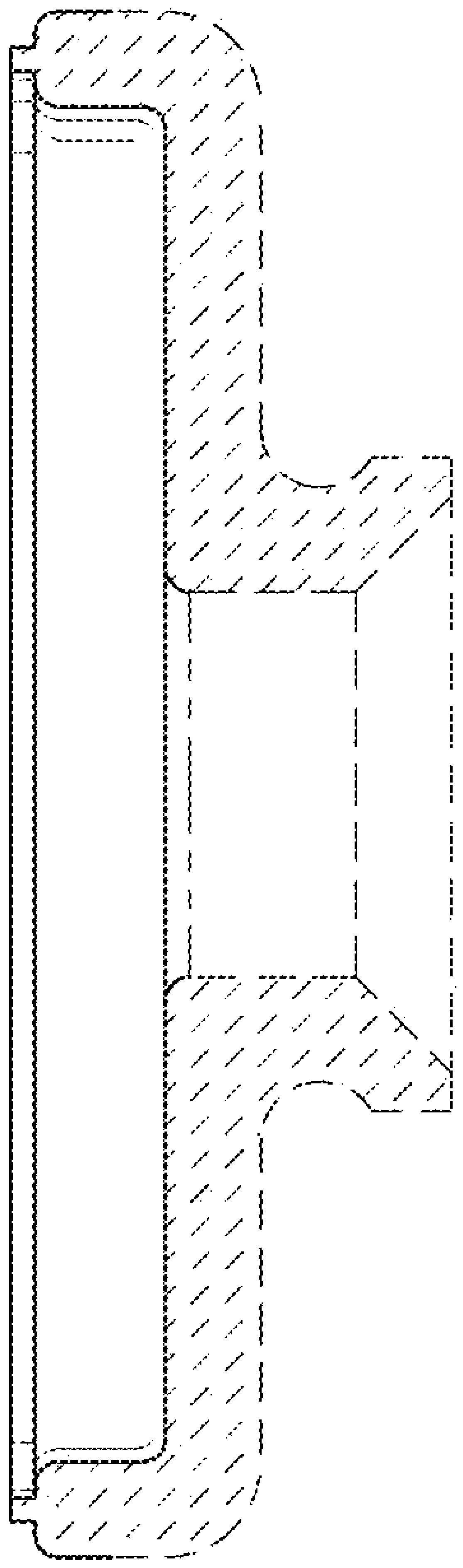


FIG. 6

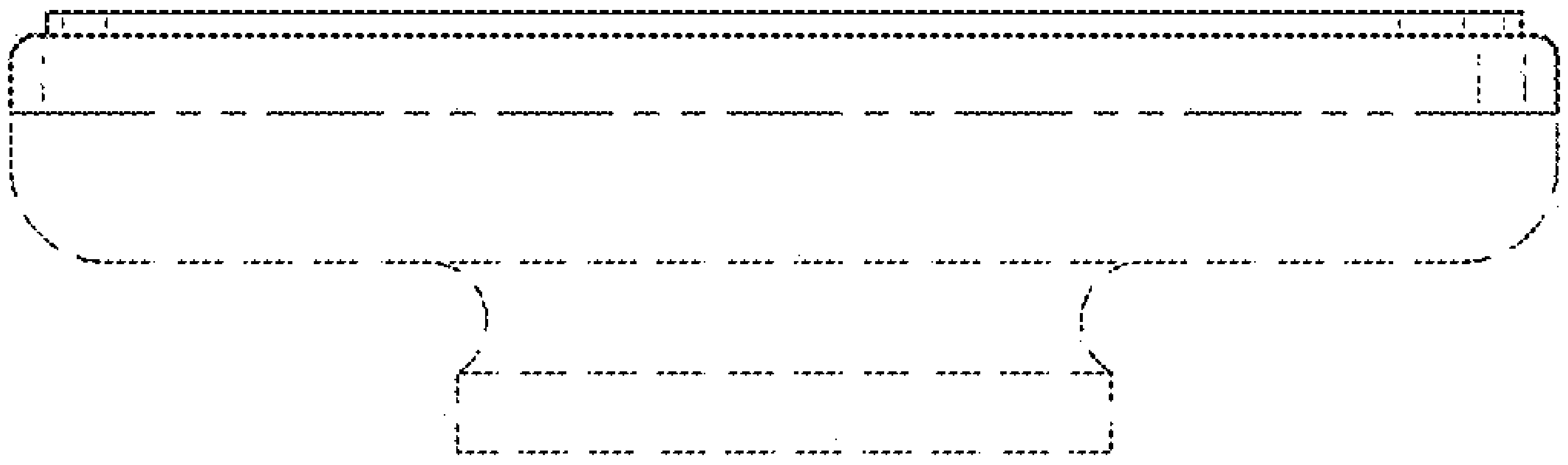


FIG. 7

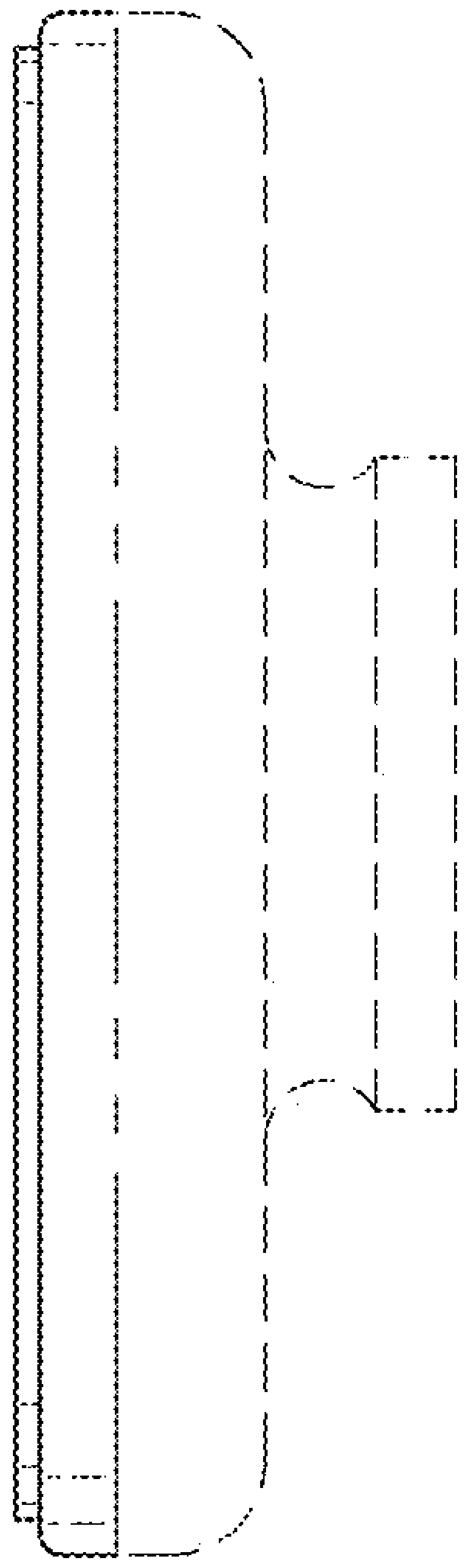


FIG. 8

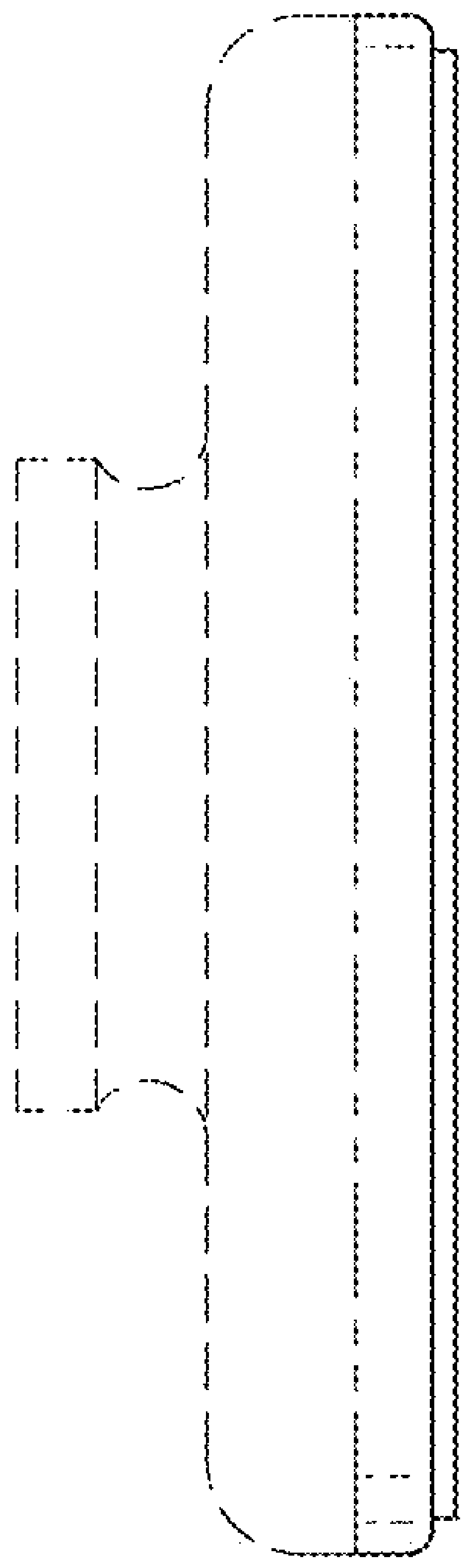


FIG. 9